

Tech News

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[IEEE ESTC 2024 Best Poster Award goes to Nyake Gahein-Sama](#)

Award / September 13, 2024



We are very pleased to announce that our colleague Nyake Gahein-Sama won the Best Poster Award at this year's IEEE Electronics System Integration Technology Conference (ESTC 2024) in Berlin. He was recognized for his contribution on "Alignment Between Subsequent 3D Molding Layers for Optimized Performance of 3D Integrated Patch Antennas for Advanced Sensing Applications".

[ITRI-Chairman visits Fraunhofer IZM](#)

September 03, 2024

High-ranking visitor from Taiwan: Prof. Tsung-Tsong Wu, Chairman of the Industrial Technology Research Institute (ITRI), met with the Institute Director, Prof. Ulrike Ganesh, and representatives of the Research Fab Microelectronics Germany (FMD) at Fraunhofer IZM on August 27, 2024. The meeting focused on the strategic direction and future cooperation between the two leading research institutes.

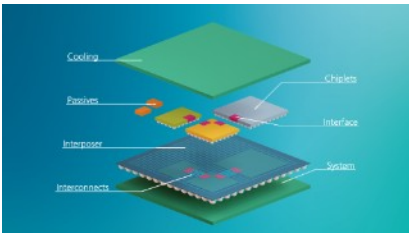


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[Paving the way for the semiconductor future: The Chiplet Center of Excellence commences operations](#)

August 05, 2024



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Three Fraunhofer Institutes have launched a forward-looking research initiative in Dresden: the Chiplet Center of Excellence (CCoE). Its purpose is to partner with industry to drive forward the introduction of chiplet technology. Researchers at the CCoE are working on several fronts for the automotive industry, developing the first workflows and methods for electronics design, demonstrator construction, and the evaluation of reliability.

[MORE INFO](#)

[Leadership duo of Professors Ulrike Ganesh and Martin Schneider-Ramelow will shape the future strategy of Fraunhofer IZM](#)

August 01, 2024

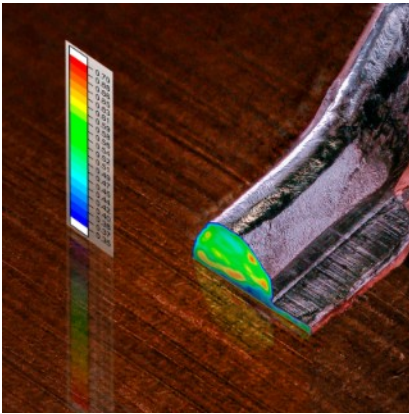


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The Fraunhofer Institute for Reliability and Microintegration IZM is proud to announce the appointment of Professor Dr Ulrike Ganesh as its Co-Director. Starting on 01 August 2024, she will join Professor Martin Schneider-Ramelow in shaping the strategic direction of the Institute.

[More reliable bonds for power semiconductors made possible with a novel way to assess wire bonding materials](#)

July 30, 2024



© Technische Universität Berlin

To understand the quality of a wire bond with a semiconductor chip, they are subjected to shear tests at the contact point where the wire meets the chip: A chisel shears off these so-called wedges, and the necessary force and resulting damage is analyzed. To learn more about what happens during shearing, researchers from the Technical University of Berlin and Fraunhofer IZM came up with an innovative simulation of the mechanical processes at work. This allows them to understand how newer and more durable wire types affect the behavior of the material and the processes and to produce a more objective and reliable assessment of the bonding quality of such novel materials.

[MORE INFO](#)

[Soitec kicks off European project to develop future high-frequency semiconductors](#)

Bernin, France / July 05, 2024



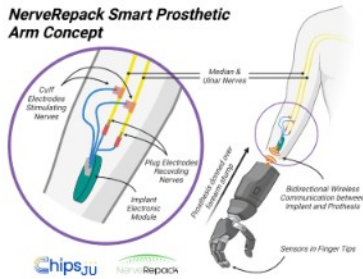
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A European research and industry consortium led by Soitec, a world leader in the design and manufacture of innovative semiconductor materials, has begun work to develop a future generation of high-frequency semiconductors based on Indium Phosphide (InP). These technologies are set to address applications ranging from photonics for AI mega data centers to radio frequency filters critical to 6G mobile communications and beyond.

[MORE INFO](#)

The revolutionary role of bioelectronics in future human medicine

June 27, 2024



Hand prostheses that restore tactile sensitivity to amputees. Sensors capable of detecting diseases prior to outbreaks. These applications could soon become part of conventional treatment thanks to microchips implanted in the body. At Fraunhofer IZM, the Technologies for Bioelectronics working group is busy developing ultra-thin biocompatible coatings for bioelectronics implants. The core aim is to enable decade-long functionality of miniature implants without the need for surgical interventions.

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EV Group and Fraunhofer IZM-ASSID expand partnership in Wafer Bonding for Quantum Computing applications

June 13, 2024



Strategic partnership kicks off with installation of EVG850 automated laser debonding system at the newly launched Center for Advanced CMOS and Heterointegration Saxony (CEASAX)

[MORE INFO](#)

© Fraunhofer IZM | Silvia Wolf

Circular WLAN routers with sustainable aluminum bodies

June 11, 2024

WLAN routers made from aluminum, equipped with a versatile multifunctional surface, and made according to the newest EU ecodesign standards: That is the objective of a German-Polish consortium of research and industry partners. With much less plastic used in the design and its circuit boards substantially brought down in size, the proposed routers offer far greater resource efficiency and circularity.

[MORE INFO](#)

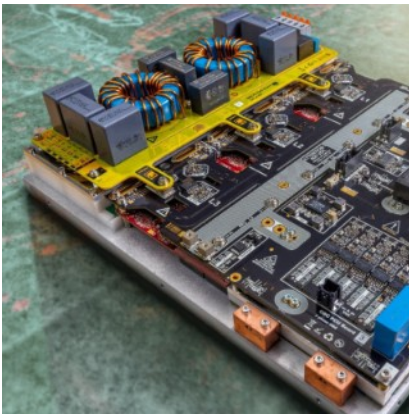
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© Tapani Jokinen

[Smaller, faster, cheaper to produce: Smart packaging for an on-board charger that is small in size, but big on performance](#)

June 06, 2024



© Fraunhofer IZM | Volker Mai

On-board chargers are the great equalizers for electric vehicle charging - and can be a game-changer for the future of e-mobility. Fraunhofer IZM has managed to bring together some of the most innovative ideas in power electronics to pave the way for a new generation of on-board chargers. Twice the performance at half the size, bidirectional capabilities, and efficiently machine-made: The resulting on-board charger is the economical ticket to the fast lane into the future.

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Source: Fraunhofer-Gesellschaft

Fraunhofer Institute for Reliability and Microintegration IZM - Tech News

Online in Internet; URL: https://www.izm.fraunhofer.de/en/news_events/tech_news.html

Date: 24.2.2025 08:04